
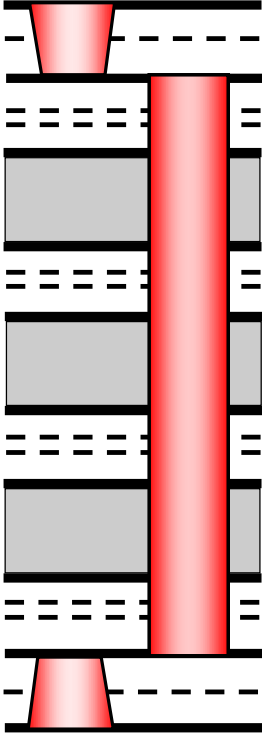


Build Up HDI (Standard)														
HDI10_1+8b+1_1,45_17.5_engl			10 - Layers							Core: 0,20 mm Cu 17.5/17.5 µm				
WE-Article No.:		1 + 8B + 1												
Customer:														
layer description		configuration			Raw-Material	CU	PREPREG	Final Thickness	Customer requirements					
Customer	WE							[µm]	[µm]					
	TOP/VS						Foil	12 µm ¹⁾		12				
									1 x 1080	60				
	2						Foil	9 µm		30				
									2 x 1080	140				
	3							17.5 µm		16				
							0,200 mm			200				
	4							17.5 µm		16				
									2 x 1080	134				
	5							17.5 µm		16				
				0,200 mm			200							
	6				17.5 µm		16							
						2 x 1080	134							
	7				17.5 µm		16							
				0,200 mm			200							
	8				17.5 µm		16							
						2 x 1080	140							
	9				17.5 µm		16							
				0,200 mm			200							
	BOT/RS				17.5 µm		16							
						2 x 1080	134							
				Foil	9 µm		30							
						1 x 1080	60							
				Foil	12 µm ¹⁾		12							
					1) copper thickness outer layers: appr. 55 µm									
					total material thickness: 1448									
					Note: Lamination thickness for Prepregs depending on layout characteristics.									
final lamination thickness:		1,45	+/-	0,11	mm	Date:		Engineer:						
thickness with electro plated Cu:		1,54	+/-	0,14	mm									
total thickness with soldermask		1,60	+/-	0,16	mm									
customer requirement			+/-		mm	point:								
prepared: on 27.03.2006 by S. Keller			checked: on 04.05.2006 by M.Kress			approved: on 04.05.2006 by R.Schönholz			revision 00 page: 13+					